			W
Advisory Action	Application No.	Applicant(s)	
	10/076,355	YAMASHITA, TOMIO	
	Examiner	Art Unit	
	Hung K. Vu	2811	
The MAILING DATE of this communication appe	ears on the cover sheet with the c	correspondence addr	ess
THE REPLY FILED 01 October 2003 FAILS TO PLACE Therefore, further action by the applicant is required to a final rejection under 37 CFR 1.113 may only be either: (condition for allowance; (2) a timely filed Notice of Appe Examination (RCE) in compliance with 37 CFR 1.114.	avoid abandonment of this application appl	cation. A proper rep ich places the applic	ly to a ation in
PERIOD FOR RE	EPLY [check either a) or b)]		
a) The period for reply expires 3 months from the mailing date of b) The period for reply expires on: (1) the mailing date of this Adevent, however, will the statutory period for reply expire later the ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS 706.07(f). Extensions of time may be obtained under 37 CFR 1.136(a). The data have been filed is the date for purposes of determining the period of externion of the status of the shortener of the status of th	visory Action, or (2) the date set forth in the nan SIX MONTHS from the mailing date of FILED WITHIN TWO MONTHS OF THe ate on which the petition under 37 CFR 1. It is sion and the corresponding amount of the distatutory period for reply originally set in	of the final rejection. E FINAL REJECTION. So 136(a) and the appropriate Fee. The appropriate extention or (ee MPEP extension fee ension fee under 2) as set forth in
1. A Notice of Appeal was filed on Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.			
$2. \boxtimes$ The proposed amendment(s) will not be entered to	pecause:		
(a) Methey raise new issues that would require furth	ner consideration and/or search	(see NOTE below);	
(b) \square they raise the issue of new matter (see Note	below);		
(c) they are not deemed to place the application issues for appeal; and/or	in better form for appeal by ma	terially reducing or s	implifying the
(d) they present additional claims without cance	eling a corresponding number of	finally rejected clain	าร.
NOTE: See Continuation Sheet.			
3. Applicant's reply has overcome the following reje	ction(s):		
4. Newly proposed or amended claim(s) would canceling the non-allowable claim(s).	d be allowable if submitted in a s	separate, timely filed	amendment
The a)☐ affidavit, b)☐ exhibit, or c)☒ request for reconsideration has been considered but does NOT place the application in condition for allowance because: <u>See Continuation Sheet</u> .			
6. The affidavit or exhibit will NOT be considered be raised by the Examiner in the final rejection.	ecause it is not directed SOLELY	to issues which we	re newly
7. For purposes of Appeal, the proposed amendmen explanation of how the new or amended claims v			and an
The status of the claim(s) is (or will be) as follows			
Claim(s) allowed:			
Claim(s) objected to:			
Claim(s) rejected: <u>1,2,4,6-10 and 12-14</u> .			
Claim(s) withdrawn from consideration:			
8. The proposed drawing correction filed on is	s a) approved or b) disap	proved by the Exam	iner.
☐ Note the attached Information Disclosure Statement(s)(PTO-1449) Paper No(s)			
10. Other:	, , , , , , , , , , , , , , , , , , , ,	Hung Ch	
		HUNG VU PATENT EXAL	11NER

U.S. Patent and Trademark Office PTOL-303 (Rev. 04-01)

Continuation Sheet (PTOL-303) 110/076,355

Application No.

• Continuation of 2. NOTE: Extensive amendments to Claim 12 raise new issues that would require further consideration and/or search.

Continuation of 5. does NOT place the application in condition for allowance because: The specification does not disclose a lower wiring layer having an opening, conductive portion filling the opening and at least one dielectric member embedded in the conductive portion nor disclose an upper wiring layer having an upper opening, an upper conductive portion filling the upper opening and at least one dielectric member embedded in the upper conductive portion, as recited in Claims 1 and 6. Applicant asserts that the specification disclose the claimed invention. This argument is not convincing because the specification only discloses the lower wiring layer is the combination of the dielectric layer (10) and the pad (11) and the upper wiring layer is the combination of the dielectric layer (30) and the pad (31). There is no disclosure of the wiring layer having an opening, conductive portion filling the opening and at least one dielectric member embedded in the conductive portion. Since the wiring layer is the combination of the dielectric and the pad, the only place where the opening would be is where the dielectric member (11i or 31i) located. As a result, a lower wiring layer has an opening in which a first dielectric member (11i) filling the opening, and an upper wiring layer has an upper opening in which a second dielectric member (31i) filling the upper opening. There is no conductive portion filling the opening because the first dielectric member (11i) is already filled the upper opening.